Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	6765	premold\$5 pre adj mold\$5 pre-mold\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/14 11:37
L2	67780	lead\$4 adj frame lead\$4-frame	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/14 11:37
L3	54364	flip adj chip flip-chip bga ball adj grid ball-grid	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/14 11:38
L4	88	1 and 2 and 3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/14 11:38
L5	61	4 and (@ad < "20030211")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/14 12:01
L6	2	"6392429".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/14 12:01
L7	253775	mosfet or (metal adj (oxide insulat\$4) adj semiconducor adj (fet or field)) or pmos or cmos or nmos or misfet	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/14 12:02
L8	2147	1 and (L7 source drain gate)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/14 12:02
L9	0	6 and (L7 source drain gate)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/14 12:55

L10	1	6 and ("34")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/14 12:55
S18 3	33098	flip adj chip flip-chip	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/14 11:37
S18 4	67745	lead\$4 adj frame lead\$4-frame	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/10 20:13
S18 5	6763	premold\$5 pre adj mold\$5	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/10 20:15
S18 6	4768737	opening aperature window expos\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/10 20:21
S18 7	10	S184 and S185 with S186 and S183	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/10 20:21
S18 8	5182093	opening aperature window expos\$4 cavity	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/10 20:21
S18 9	14	S184 and S185 with S188 and S183	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/10 20:21
S19 0	67745	lead\$4 adj frame lead\$4-frame	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/10 20:21
S19 1	6763	premold\$5 pre adj mold\$5	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/10 20:32

S19 2	102	S191 near4 S190	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/10 20:21
S19 3	85	S192 and (@ad < "20040203")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/10 20:34
S19 4	9	S189 and (@ad < "20040203")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/10 20:22
S19 5	3734214	mold\$5 encapsulat\$4 packag\$4 epoxy resin	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/10 20:32
S19 6	781	S195 with S186 with S183	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/10 20:33
S19 8	141	S196 and S184	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/10 20:33
S19 9	106	S198 and (@ad < "20040203")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/11 17:07
S20 1	33098	flip adj chip flip-chip	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/11 17:07
S20 2	67745	lead\$4 adj frame lead\$4-frame	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/11 17:08
S20 5	5202980	top cover cap lid hinge	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/11 17:12

S20 6	3134	S201 and S202 and S205	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/11 17:10
S20 7	2374476	chip package ic integrated adj circuit die dice	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/11 17:10
S20 8	2646	S201 and S202 and S207 same S205	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/11 17:10
S20 9	2646	S201 and S202 and (S207 S201) same S205	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/11 17:10
S21 0	929	S201 same S202 and (S207 S201) same S205	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/11 17:12
S21 1	605	S210 and (@ad < "20030211")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/11 17:12
S21 2	3146685	cover cap lid hinge	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/11 17:13
S21 3	562	S201 same S202 and (S207 S201) same S212	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/11 17:13
S21 '4	363	S213 and (@ad < "20030211")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR .	ON	2006/08/11 17:13
S21 5	1270486	cap lid hinge	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/11 17:13

S21 6	109	S201 same S202 and (S207 S201) same S215	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/11 17:13
S21 7	72	S216 and (@ad < "20030211")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/11 17:14
S21 8	29	("5386342").PN. OR ("6313521"). URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/08/11 18:06
S21 9	29	("5386342").PN. OR ("6313521"). URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/08/11 18:37
S22 0	288	S214 not S217	US-PGPUB; USPAT; USOCR	OR	OFF	2006/08/11 19:14
S22 1	1	"5818102".pn.	US-PGPUB; USPAT; USOCR	OR ·	OFF	2006/08/11 19:15
S22 2	1	S221 and S201 and S202	US-PGPUB; USPAT; USOCR	OR	OFF	2006/08/11 19:15